

## Capacitor Materials

### ET1805



## Pb-Free Solderable End Termination

#### Description:

ET1805 is a Pb free solderable Ag/Pd plus 5%Pt end termination designed for use on MLCC (multilayer ceramic chip capacitors). It offers excellent solderability and adhesion.

ET1805 is supplied at a viscosity suitable for machine dip and blot or no blot applications

#### ● Key Benefits :

- Does not contain lead or cadmium
- Suitable rheology for machine dip application
- For higher leach resistance application
- Compatible on titanate ceramic bodies

#### ● Typical Properties:

##### Viscosity :

30-40 Kcps; Brookfield RVT,  
SC4-14 spindle and 6R cup at 10 RPM, 25°C.

##### Solids :

81.5 ± 1.0%

##### FOG :

≤ 10 μm (6<sup>th</sup> scratch)

##### Solderability :

62Sn/36Pb/2Ag @ 230°C  
5 sec dip, RMA flux

100% Solder Coverage

##### Leach Resistance:

SAC405 @ 260°C  
30 sec dip, RMA flux

No loss of material

#### ● Recommended Processing Guidelines:

##### Drying :

Dry in 180°C profile, 10 minute @ peak  
20 minute cycle

##### Firing:

Fires at 780-810°C peak temperature  
Dwell time of 5-6 minutes at peak

##### Thinner :

RV-372 (Terpineol)

##### Warranty:

Material guaranteed to meet specifications  
for 6 months from date of shipment.

##### Storage :

Store in a dry location at 5-25°C.

**DO NOT REFRIGERATE.**

Allow paste to come to room temperature  
prior to opening.

Spatulate well before using.

YY0810.1

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The descriptions and engineering data shown here have been compiled by Heraeus using commonly-accepted procedures, in conjunction with modern testing equipment, and have been compiled as according to the latest factual knowledge in our possession. The information was up-to date on the date this document was printed (latest versions can always be supplied upon request). Although the data is considered accurate, we cannot guarantee accuracy, the results obtained from its use, or any patent infringement resulting from its use (unless this is contractually and explicitly agreed in writing, in advance). The data is supplied on the condition that the user shall conduct tests to determine materials suitability for a particular application.

#### Americas

Heraeus Materials Technology LLC  
Thick Film Materials Division  
24 Union Hill Road  
West Conshohocken, PA 19428  
USA  
Phone: +1 (610) 825-6050  
E-Mail: [techservice.hcd@heraeus.com](mailto:techservice.hcd@heraeus.com)  
Internet: [www.thickfilm.net](http://www.thickfilm.net)

#### Europe

W.C. Heraeus GmbH  
Thick Film Materials Division  
Heraeusstr. 12-14  
63450 Hanau  
Germany  
Phone: +49 (6181) 35-5466  
E-mail: [th-info@heraeus.com](mailto:th-info@heraeus.com)  
Internet: [www.heraeus-thickfilm.com](http://www.heraeus-thickfilm.com)

#### Asia

Heraeus Materials Technology  
Shanghai Ltd.  
No. 1 Guang Zhong Road  
Zhuangqiao Town, Minhang District  
Shanghai 201108  
People's Republic of China  
Phone: + 86 (21) 3357-5688  
E-Mail: [th.hmts@heraeus.com](mailto:th.hmts@heraeus.com)  
Internet: [www.heraeus-thickfilm.com](http://www.heraeus-thickfilm.com)